## DATALOGIC JOINS EURONEXT TECH LEADERS

Datalogic is happy to announce its participation in the Euronext Tech Leaders initiative dedicated to high-growth and leading Tech companies

Milan, 15th June 2023 - Datalogic S.p.A., listed in the Euronext STAR Milan Segment of the Italian Stock Exchange organised and managed by Borsa Italiana S.p.A. and global leader in the automatic data capture and industrial automation segments, is proud to join Euronext Tech Leaders, Euronext Tech Leaders | euronext.com, the new initiative dedicated to high-growth and leading Tech companies.

Euronext's rich Tech ecosystem brings together 700+ Tech companies listed on Euronext markets with 660+ alumni of its pre-IPO programmes and a large international investor base financing all growth profiles of Tech companies.

Euronext Tech Leaders is composed of 120+ high-growth and leading Tech companies, each meeting a specific set of criteria to qualify. It complements Euronext's existing Tech offer and aims to strengthen the European Tech sector and be a catalyst for the next generation of Tech leaders.

Valentina Volta, Group CEO of Datalogic: "We are excited to be part of this segment, which strives to promote European technological excellence globally. In its more than 50 years of life, Datalogic has demonstrated its ability to consistently innovate, anticipate trends and constantly evolve through the development of increasingly innovative and advanced solutions, thus the inclusion in the Euronext Tech Leaders represents the recognition by the financial community of our tech competitive advantage. We hope that the efforts made by Euronext to support this segment can play a crucial role in increasing the recognition and value of European tech stocks, not yet as widely recognized as their American counterparts, who benefit from a dedicated and highly liquid global market".

As a Euronext Tech Leader, Datalogic will benefit from the suite of services developed by Euronext and its partners to support participants along their listing journey.

